



- Drafts
- Pending
- Active
 - L1: (17) (microelectromechanical "MEMS" nanoelectromechanical "NEMS" nanomechanical) and (sacrific...
 - L2: (12) (microelectromechanical "MEMS" nanoelectromechanical "NEMS" nanomechanical) and (sacrific...
 - L3: (0) (microelectromechanical "MEMS" nanoelectromechanical "NEMS" nanomechanical) and (sacrific...
 - L4: (8) (microelectromechanical "MEMS" nanoelectromechanical "NEMS" nanomechanical) and (sacrific...
- Failed
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 - S1: (1) (microelectromechanical "MEMS" nanoelectromechanical "NEMS" nanomechanical) and (sacrific...
 - S3: (10) (microelectromechanical "MEMS" nanoelectromechanical "NEMS" nanomechanical) and (sacrific...
 - S4: (0) (nanoelectromechanical "NEMS" nanomechanical) and (sacrificial) and wet near etch\$3 and (...)
 - S5: (0) (nanoelectromechanical "NEMS" nanomechanical) and (sacrificial) and wet near etch\$3 and (...)
 - S6: (13) (nanoelectromechanical "NEMS" nanomechanical) and (sacrificial) and wet near etch\$3 and (...)
 - S2: (26) (microelectromechanical "MEMS" nanoelectromechanical "NEMS" nanomechanical) and (sacrific...
 - S7: (10) (microelectromechanical "MEMS" nanoelectromechanical "NEMS" nanomechanical) and (sacrific...
 - S8: (1) ("6589717").PN.
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Default operator: OR

Highlight all hit terms initially

(microelectromechanical "MEMS" nanoelectromechanical "NEMS" nanomechanical) and (sacrificial SiO₂ silicon near dioxide) and wet near etch\$3 and (carbon near film)

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U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Ref
1	<input type="checkbox"/>	US 20050164412 A1	20050728	17	Custom electrodes for molecular memory and logic devices	438/1		
2	<input type="checkbox"/>	US 6844623 B1	20050118	11	Temporary coatings for protection of microelectronic devices during packaging	257/723	257/682; 257/687; 257/701;	
3	<input type="checkbox"/>	US 6404028 B1	20020611	9	Adhesion resistant micromachined structure and coating	257/415	257/419; 257/619	
4	<input type="checkbox"/>	US 6379988 B1	20020430	24	Pre-release plastic packaging of MEMS and IMEMS devices	438/51	257/E21.502; 257/E21.504; 257/E23.124;	
5	<input type="checkbox"/>	US 6335224 B1	20020101	11	Protection of microelectronic devices during packaging	438/114	257/E21.502; 257/E23.119; 438/113;	
6	<input type="checkbox"/>	US 6096149 A	20000801	9	Method for fabricating adhesion-resistant micromachined devices	156/155	156/247; 156/267; 156/310;	
7	<input type="checkbox"/>	US 5970315 A	19991019	12	Microelectromechanical structure and process of making same	438/52	438/700; 438/710; 438/745;	
8	<input type="checkbox"/>	US 5825385 A	19981020	76	Constructions and manufacturing processes for thermally activated print heads	347/56		

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